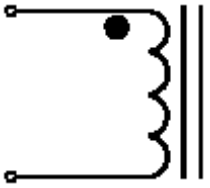
Inductor

multicomp PRO

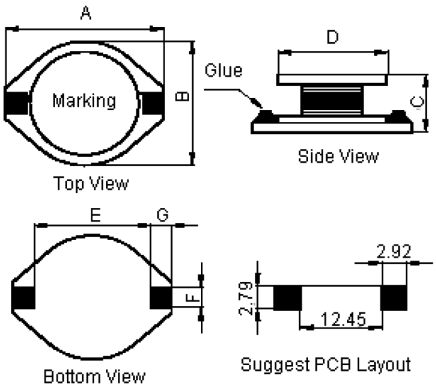
RoHS Compliant

Schematic Diagram



Note:
1. Wire Ø0.2mm × 1P 2UEWF 155°C
2. 400.5TS (Reference)

Configurations and Dimensions



A	18.54mm (Max.)
B	15.24mm (Max.)
C	12mm (Max.)
D	12.7 ±0.3mm
E	12.92mm (Ref.)
F	2.54mm (Ref.)
G	2.54mm (Ref.)

Dimensions : Millimetres

Test Data for Mechanical

Test Item	A mm	B mm	C mm	D mm	E mm	F mm	G mm
Specification	**18.54 (Max.)**	**15.24 (Max.)**	**12 (Max.)**	**12.7 ±0.3**	**12.92 (Ref.)**	**2.54 (Ref.)**	**2.54 (Ref.)**
1	18.13	13.93	10.99	12.74	12.93	2.59	2.54
2	18.09	13.95	11.01	12.76	13.01	2.46	2.52
3	18.16	14.01	10.98	12.69	12.96	2.53	2.48
4	18.07	13.98	10.99	12.78	12.91	2.61	2.53
5	18.14	14	11.02	12.71	12.95	2.44	2.61
Average	**18.12**	**13.97**	**11**	**12.74**	**12.95**	**2.53**	**2.54**

Electrical Characteristics

Test Condition		
100kHz / 0.25V	L	8mH ±10%
at 25°C	DCR	8Ω (Maximum)
100kHz / 0.25mA Irms = 0.25A	ΔT	Temperature rise 40°C (Max.)

Operating temperature : -40°C to +125°C

Reliability Test

Test Item	Specifications	Test Method and Remarks
Operating temperature range	-55°C to +130°C	Including temperature rise due to self-generated heat.
Storage condition	Ambient temperature : 0°C to 40°C Humidity : Below 70% RH	To maintain the solderability of terminal electrodes, care must be taken to control temperature and humidity in the storage area.
Moisture sensitivity	Appearance : No abnormality No damage DCR change : Within ±5% Inductance change : Within ±5%	According to J-STD-020B level 3 Test condition : 60°C 60% RH Test duration : 40 hrs Recovery : 1 to 2 hours of recovery under the standard condition after the removal from the test chamber.
Solderability	All termination shall exhibit a continuous solder coating free from defects for a minimum of 95% of the surface area of any individual lead.	According to J-STD-002B Steam aging category : 97°C 98% RH Steam aging duration : 8 hrs Solder : Lead-free solder Solder temperature : 260 ±5°C Dip time : 5 +0 / -0.5s

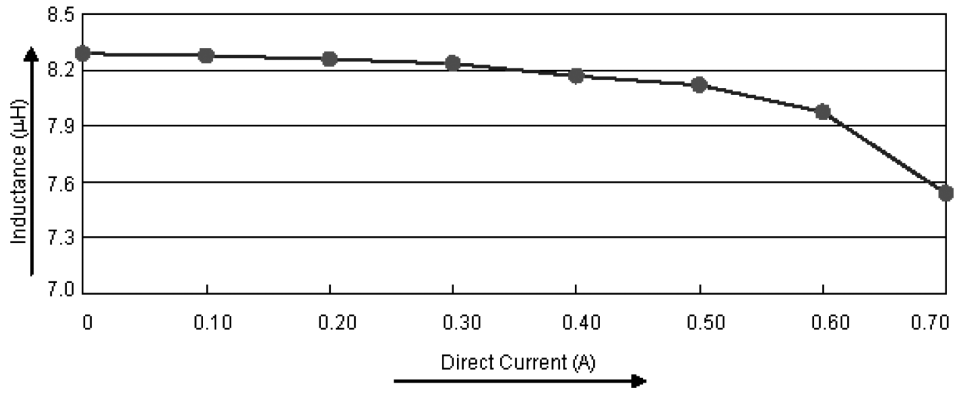
Test Data for Electrical

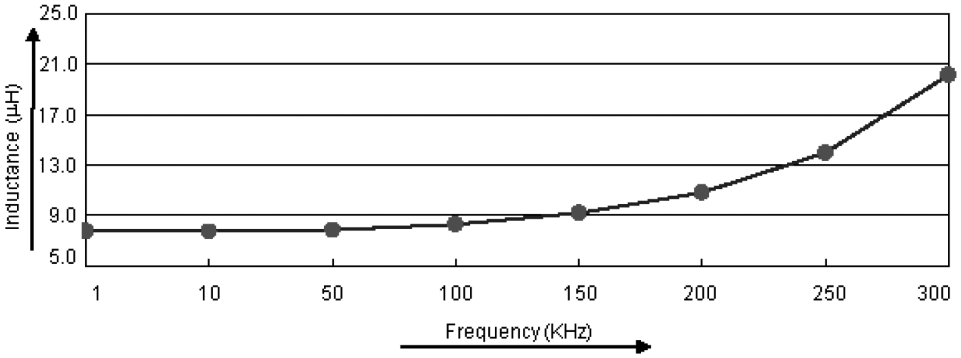
Test Item	L µH	DCR Ω	ΔT
Condition	100kHz / 0.25V	at 25°C	100kHz / 0.25V Irms = 0.25A
Specification	8 ±10%	8 (Max.)	Temperature rise 40°C (Max.)
1	8.36	6.23	OK
2	8.28	6.24	
3	8.27	6.23	
4	8.32	6.25	
5	8.3	6.24	
Average	**8.31**	**6.238**	**OK**

Material List

No.	Item	Material Description
1	Core	T2 DR12.7 × 10C B6.5 F7.0
2	Wire	Ø0.2mm × 1P 2UEWF 155°C
3	Solder (Lead Free)	Sn99.3% / Cu0.7%
4	Glue	TH320
5	Base	DAP HD127-3

Electric Characteristics





Part Number Table

Description	Part Number
Inductor, SMD, 8MH, 10%	MCBF7344-802KU

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